

1                   **ABSTRACT OF THE INVENTION**

2                   The present invention relates to enhanced protection of the active surface and the  
3 bond wires or ball array of a microelectronic device, and to thermal management of the  
4 microelectronic device as it is package with a printed circuit board (PCB) or other substrate.  
5 The enhanced protection and thermal management are accomplished with a high-temperature  
6 thermal grease that is glob topped or encapsulated over the bond wires or ball array, and the  
7 active surface of the microelectronic device. The high-temperature thermal grease exchanges  
8 heat, particularly by conduction, away from the active surface of the microelectronic device  
9 as well as away from the bond wires.

10  
11  
12  
13  
14  
15                  G:\DATA\PAT\11675184.2PA